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TECHNOLOGY CENTER 2800

PATENT APPLICATION

**RESPONSE UNDER 37 CFR §1.116
EXPEDITED PROCEDURE
TECHNOLOGY CENTER ART UNIT 2826**

15/01/03
Jmepa
2/12/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Nobuaki HASHIMOTO

Group Art Unit: 2826

Application No.: 09/856,924

Examiner: T. N. Tran

Filed: May 30, 2001

Docket No.: 109681

For: SEMICONDUCTOR DEVICE AND METHOD OF FABRICATING THE SAME,
CIRCUIT BOARD, AND ELECTRONIC INSTRUMENT

AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR §1.116

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

In reply to the November 6, 2002 Office Action, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 20-32 without prejudice to or disclaimer of the subject matter contained therein. Applicant reserves the right to file a Divisional Application to pursue these claims.

Please replace claim 1 as follows:

1. (Twice Amended) A semiconductor device comprising:
a substrate including a plurality of holes and a surface over which an
interconnecting pattern is formed, part of the interconnecting pattern being superposed over
the holes;

CJQ